

Performance of Ultrathin Dielectric Materials to Be 3M Topic at IPC Printed Circuits Expo

"Electrical Performance Advantages of Ultrathin Dielectric Materials Used for Power-Ground Cores in High-Speed, Multilayer Printed Circuit Boards" will be presented at IPC Printed Circuits Expo 2003 by Joel Peiffer, engineering specialist with the 3M Organic Materials Technology Center. Peiffer co-authored the paper with Bob Greenlee of Merix Corp. and Istvan Novak of Sun Microsystems. The electrical performance improvements, as well as the required changes in processing and material handling required to successfully manufacture multilayer printed circuit boards utilizing ultrathin dielectrics in a high-volume production setting, will be presented at the Thursday, March 27, session.

3M will exhibit its embedded capacitor material at booth 1656C in the Technology Center at the Expo, which will be at the Long Beach (Calif.) Convention Center.

"Electrical Performance Advantages of Ultrathin Dielectric Materials Used for Power-Ground Cores in High-Speed, Multilayer Printed Circuit Boards"

3M is an active member of the Advanced Embedded Passives Technology (AEPT) Consortium, which last month announced a new model for combining materials, design and processing technology for embedding passive components into circuit board substrates.

For more information on 3M embedded capacitor material, contact Bill Balliette, new product development manager, 3M Microinterconnect Systems Division, (512) 984-7324, or go to www.3M.com/microflex.

3M Microinterconnect Systems Division provides custom, high-performance flexible circuits for today's demanding electronics applications, including ink-jet printers, hard disk drives, optoelectronics, liquid crystal displays, medical, bio-analytical, IC packaging and other fine-pitch interconnect applications. 3M's technology, materials and process expertise enable its offering of circuits with one- and two-metal layer construction, and liquid crystal polymer or polyimide substrates. The division also supplies high-density, multilayer interconnect solutions for electronics and photonics packaging. These high-density laminated chip packages provide breakthrough density and outstanding electrical performance optimized for ASICs in high bandwidth and networking applications.

About 3M

3M is a \$16 billion diversified technology company with leading positions in consumer and office; display and graphics; electronics and telecommunications; health care; industrial; safety, security and protection services; transportation and other businesses. Headquartered in St. Paul, Minnesota, the company has operations in more than 60 countries and serves customers in nearly 200 countries. 3M is one of the 30 stocks that make up the Dow Jones Industrial Average and also is a component of the Standard & Poor's 500 Index. For more information about 3M, go to www.3M.com/profile/pressbox/index.jhtml.

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